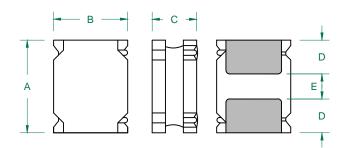
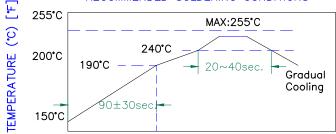
TYS252010L4R7M-10

PHYSICAL DIMENSIONS:

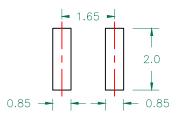
Α	2.50	±	0.10
В	2.00	±	0.10
С	1.00		MAX.
D	0.80	±	0.20
F	0.80	+	0.20

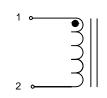


RECOMMENDED SOLDERING CONDITIONS



LAND PATTERNS FOR REFLOW SOLDERING



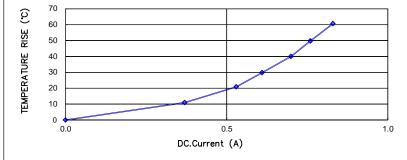




ELECTRICAL SPECIFICATION

	Min	Тур	Max
INDUCTANCE (uH) L @ 100KHz/1V ± 20%	3.76	4.70	5.64
DCR (Ω)			0.563
Saturation Current(A)		1.15	0.95

CHARACTERISTICS OF TEMPERATURE RISE



UNCONTROLLED DOCUMENT

SRF (MHz)	40
Temperature Rise	
Current (A)	0.70

NOTES: UNLESS OTHERWISE SPECIFIED

1.OPERATING TEMPERATURE RANGE: -40°C TO +125°C (INCLUDING SELF-HEATING) .

2.STORAGE TEMPERATURE RANGE (PACKAGING CONDITIONS): -10°C TO +40°C AND RH 70% (MAX.)

3.UNLESS OTHERWISE SPECIFIED, THE STANDARD ATMOSPHERIC CONDITIONS FOR MEASUREMENT/TEST AS:
A. AMBIENT TEMPERATURE: 20±15°C.

B. RELATIVE HUMIDITY: 65%±20%.

4.DEFINITION OF SATURATION CURRENT (ISAT): DC CURRENT AT WHICH THE INDUCTANCE DROPS \leq 30% FROM ITS VALUE WITHOUT CURRENT.

5.DEFINITION OF TEMPERATURE RISE CURRENT (IRMS): DC CURRENT THAT CAUSES THE TEMPERATURE RISE ($\Delta \text{T} \leq 40\,^{\circ}\text{C}$) FROM 20°C AMBIENT.

DIMENSIONS ARE IN mm . This print is the property of Laird			This print is the property of Laird	
				Tech, and is loaned in confidence subject to return upon request and
				with the understanding that no
				copies shall be made without the written consent of Laird Tech. All
				rights to design or invention are
				reserved.
				PROJECT/PART NUMBER: REV PART TYPE: DRAWN BY:
				TYS252010L4R7M-10 B POWER QIU
В	CHANGE TEMP FROM −25°C~+125°C	12/27/12	QIU	DATE: 07/06/12 SCALE: NTS SHEET:
Α	ORIGINAL DRAFT	07/06/12	QIU	
REV	DESCRIPTION	DATE	INT	

CURRENT VS INDUCTANCE DROP IN RATES

